



Material Content Data Sheet



Sales Product Name		TLF50251EL		Issued		31. July 2018		
MA#		MA001896624						
Package		PG-SSOP-14-3		Weight*		82.98 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.797	2.17	2.17	21662	21662
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		104	
	non noble metal	zinc	7440-66-6	0.034	0.04		415	
	non noble metal	iron	7439-89-6	0.689	0.83		8304	
wire	non noble metal	copper	7440-50-8	27.978	33.72	34.60	337162	345985
	noble metal	gold	7440-57-5	0.168	0.20	0.20	2029	2029
encapsulation	organic material	carbon black	1333-86-4	0.100	0.12		1203	
	plastics	epoxy resin	-	4.591	5.53		55330	
	inorganic material	silicondioxide	60676-86-0	45.215	54.48	60.13	544886	601419
leadfinish	non noble metal	tin	7440-31-5	0.976	1.18	1.18	11763	11763
plating	noble metal	silver	7440-22-4	0.768	0.93	0.93	9251	9251
glue	plastics	epoxy resin	-	0.164	0.20		1973	
	noble metal	silver	7440-22-4	0.491	0.59	0.79	5918	7891
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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